



High efficiency defoamer for epoxy

Better BP-5066

Product Description:

Better BP-5066 It is a specialized defoamer for epoxy with a 3% active content. It is a special organic silane solution with excellent compatibility with epoxy resin, and has excellent defoaming and defoaming effects. It is particularly suitable for the defoaming and defoaming of two component epoxy adhesives and epoxy coatings. Product Features:

◆ Good compatibility, especially suitable for highly transparent epoxy systems (AB adhesive, jewelry adhesive, crystal adhesive, LED adhesive, potting adhesive, etc.; colorless and colored transparent epoxy coatings), with high defoaming efficiency and long-lasting defoaming effect;

◆ No yellowing side effects, more significant defoaming effect in epoxy systems such as crystal adhesive and potting adhesive;

◆ A small amount of addition will produce excellent defoaming effect.

Product properties:

appearance	Transparent liquid
Active fraction%	1-3
solvent	Methyl isobutyl ketone (85-90%), DIBK (0-10%)
proportion	0.81g/ml (25°C)
Flash point	16.5°C

Application scope:

Suitable for floor coatings, AB adhesives, jewelry adhesives, crystal adhesives, LED adhesives, potting adhesives, etc. in solvent based epoxy systems; Colorless, colored transparent epoxy coating.

This product has excellent performance in high polarity based systems (especially solvent based wood varnish) – two component polyurethane systems, nitro systems, acid cured amino or epoxy systems, etc. It can quickly and effectively eliminate bubbles generated by auxiliary processes such as mixing, pumping, and spraying.

Addition amount and usage method:

0.1~1.0% (For the total amount of formula, it should be added in the final stage of production and dispersed evenly.)



Application Cases of Special High Efficiency Defoamer in Transparent Epoxy System:

The comb shaped special chemical structure of this product effectively balances compatibility with epoxy resin systems and defoaming effects. It can quickly capture bubbles and diffuse into the liquid film of bubbles, disrupting their stability. It has been widely used in various fields of epoxy systems, providing an effective solution for formula customization personnel to solve the problem of bubbles.

1) Epoxy AB adhesive - reduces defects in the curing system and can increase the tensile and shear strength of the adhesive after setting by 24% -60%.

Recipe	Weight (%)
Epoxy resin 828	93.0
BGE	6.5
Deformer	0.5
Total	100.0

2) Epoxy jewelry adhesive - improves transparency, simplifies molding process, and enhances product grade.

Recipe	Weight (%)
Epoxy resin 828	93.0
BGE	3.4
di-n-butyl phthalate (DBP)	3.0
Deformer	0.6
Total	100.0

3) Epoxy potting adhesive - increases the wettability of the substrate, reduces defects within the system, and improves the market competitiveness of the product.

Recipe	Weight (%)
Epoxy resin 828	89.0
BGE	3.6
di-n-butyl phthalate (DBP)	6.0
Thinner	1.0
Deformer	0.4
Total	100.0

4) Epoxy floor coating - reduces surface defects, improves coating gloss, freshness, and durability.

Recipe	Weight (%)
Epoxy resin 828	90.0
AGE	4.0



di-n-butyl phthalate (DBP)	3.4
Colour paste	trace amount
Thinner	2.0
Flow agent	0.2
Deformer	0.4
Total	100.0

5) Epoxy coating varnish – reduces surface defects, improves coating adhesion, gloss, and fullness.

Recipe	Weight (%)
Epoxy resin E-44	92.0
AGE	5.0
Thinner	2.0
Flow agent	0.4
Deformer	0.6
Total	100.0

6) Epoxy prepreg – promotes the bonding between the matrix resin and fiberglass, increases the destructive strength of the composite material, and does not affect the cost and storage period of the prepreg. Suggested addition amount (relative to the total mass of solid resin) is 0.3% -0.6%.

Packaging and Storage:

25、200KG/barrel

Keep away from ignition sources and place in a cool and ventilated place; Under normal storage conditions, it is 24 months.

Heavy metal content:

Sb	As	Ba	Cd	Cr	Pb	Hg	Se	Zn
<5	<2.5	<10	<5	<5	<5	<5	<5	<10